# A Transparent µECoG Array for Simultaneous Recording and Optogenetic Stimulation

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Abstract—In this paper we report for the first time the design, fabrication and characterization of an optically transparent electrode array for micro-electrocorticography. We present a 49-channel  $\mu$ ECoG array with an electrode pitch of 800  $\mu$ m and a 16-channel linear  $\mu$ ECoG array with an electrode pitch of 200  $\mu$ m. The backing material was Parylene C. Transparent, sputtered indium tin oxide (ITO) was used in conjunction with e-beam evaporated gold to fabricate the electrodes. We provide electrochemical impedance characterization and light transmission data for the fabricated devices.

### I. INTRODUCTION

**S** TATE of the art tools for simultaneous optogenetic stimulation and electrophysiological recordings, such as 'optrodes' [1], are invasive and can cover only a very small fraction of the cortex with relatively few stimulation and recording sites. The importance of electrocorticography (ECoG) -- the measurement of electrical potentials on the surface of the cerebral cortex -- is growing for both brainmachine-interfaces (BMI) and as a fundamental research tool for the investigation of long-range neural circuitry and synchronization [2,3]. In this paper, we present an optically transparent  $\mu$ ECoG array, which allows optical stimulation of neural tissue immediately beneath the array (Fig. 1).

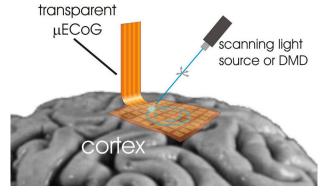


Fig. 1. Integration of  $\mu ECoG$  with optogenetics. Patterned light, e.g. from a Digital Micromirror Device (DMD), excites transfected or transgenic neural tissue underneath a transparent  $\mu ECoG$  array. Electrical activity detected by the  $\mu ECoG$  could be feedback-coupled with the light-source output to control activation states on the cerebral cortex.

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M. M. Maharbiz is a professor of Electrical Engineering and Computer Science, University of California, Berkeley, CA 94720 USA. ECoG constitutes a trade-off in invasiveness and spatial resolution between traditional scalp electroencephalography (EEG) and penetrating microelectrode recordings. In the 1950's, Jasper and Penfield pioneered ECoG [4] for presurgical evaluation of patients suffering from intractable epilepsy. Brindley and Craggs reported a correlation between voluntary movement and ECoG signals as early as 1972 [5]. More recently, the BMI community demonstrated the great promise of ECoG-based BMIs [6] for the neural control of high performance motor [7] and communication [8] prostheses, e.g. for locked-in patients. For BMI applications, the development of large area, high-resolution ECoG grids [9,10] is key.

Neural recordings constitute only part of a larger tool kit required to 'reverse engineer' the brain (i.e. to understand its normal or pathological dynamics as properties of underlying neural circuits). Ideally, it is also desirable to trigger artificial neural signals and to study how this information is transformed in the brain. A specific example of this can be seen in BMI for motor control [10]. Successful motor control is highly dependent on proper sensory feedback. In this context, it is essential to close the motor-sensory feedback loop (for example, to integrate a prosthetic limb into a patient's proprioception) and this requires information 'write-in' [11].

Neurons can be stimulated electrically but with poor spatial resolution, and stimulation artifacts render simultaneous electrophysiological recordings at the same site very difficult. Boyden and Deisseroth recently demonstrated that neurons can be rendered sensitive to stimulation by light [12]. Neurons transfected with a lightsensitive ion channel, such as channelrhodopsin, bacteriorhodopsin and halorhodopsin, can be individually modulated to either fire or suppress action potentials when illuminated at the correct wavelength.

Integration of this powerful new stimulation approach with ECoG requires the development of a transparent, flexible, and biocompatible electrode array. The fabrication of flexible transparent electrodes has to date been mainly developed for LEDs, flexible displays and solar cells. Several materials and deposition methods have been investigated to achieve the best tradeoff between transparency and conductivity. Transparent conductive oxides (TCOs) such as indium tin oxide (ITO) can be found in numerous industrial applications due to their high electrical conductivity and transparency over the entire visible spectrum [13]. However, ITO is a relatively brittle ceramic material and thus it is considered suboptimal for flexible electrodes [14]. While alternatives such as single walled carbon nanotube percolation networks [15], silver nanowire percolation networks [16] and graphene layers [17] are being investigated, ITO is a material with superior conductivity, transparency and biocompatibility [18], and is easily sputtered and patterned lithographically.

In preliminary experiments we fabricated an ECoG array using ITO as the conductor for all electrodes in the array but the large bond pads broke along stress lines at the edge of plasma-etched vias (Fig. 4a). Interestingly, ITO microelectrode pads and buried traces remained intact. In this paper, we mitigate the brittleness of ITO by confining it to the microelectrodes and to short pieces of buried interconnect traces while the long interconnect traces and bonding pads are fabricated out of ductile gold.

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### II. DESIGN

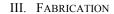
Fig. 2. Top: ECoG CAD designs (49 channel 2D array with 800  $\mu$ m pitch and 16 channel linear array with 200  $\mu$ m pitch). Bottom left: Baseline (Cr/Au/Pt stack) ECoG. Bottom right: Hybrid Au-ITO ECoG.

We have designed a 49-channel  $\mu$ ECoG array with an electrode pitch of 800  $\mu$ m and a 16-channel linear  $\mu$ ECoG with an electrode pitch of 200  $\mu$ m (Fig. 2). A 2 cm long Parylene cable was monolithically integrated with the ECoG array at the wafer level. In our prototype devices all conductors were formed by a tri-stack of chrome (10 nm Cr), gold (200 nm Au) and platinum (50 nm Pt). In the hybrid

Au-ITO devices the linear bond pad array (pad dimensions:  $100 \ \mu m \times 2500 \ \mu m$ ,  $200 \ \mu m$  pitch) and most of the conductor traces (width:  $20 \ \mu m$ ) consisted of Cr/Au (10 nm / 100 nm). However, near the microelectrode array gold overlapped with ITO (110 nm) and the electrodes were made entirely of ITO to achieve transparency (blue shaded regions in Fig. 2).

The cable was thermo-compression-bonded to a fan-out printed circuit board (PCB) in an anisotropic conductive film (ACF) bonding process. The adaptor PCB was outfitted with two 34-pin ZIF connectors (DF30FC-34DS-0.4V, Hirose) compatible with the *ZIF-Clip*® neural recording headstage amplifiers made by Tucker Davis Technologies (TDT).

The choice of biocompatible materials and the form factor of our devices allow for acute and chronic application in rodent, feline, non-human primate and in human subjects.



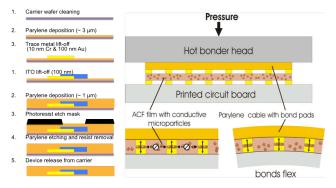


Fig. 3. Fabrication and assembly. Left: Au-ITO hybrid device fabrication process. Top right: The ACF film is thermo-compressed between complementary pad arrays. Top middle: Au-coated polymer microspheres embedded in the epoxy establish a robust electrical connection. Between adjacent pads the microparticles remain surrounded by insulating polymer that prevents shorts. Bottom right: The cured epoxy provides mechanical stability under flexion.

### A. Waferlevel Fabrication

The wafer-level fabrication process is shown in Fig. 3 (left). A 3  $\mu$ m thick layer of Parylene C (poly(para-chloroxylylene) layer was deposited on a 4" silicon carrier wafer using a (Specialty Coating Systems) Parylene System Model 2010 under conditions shown in Table 1. Enclosing the wafer holder inside an ultra-fine stainless steel mesh (McNichols, square weave, stainless steel type 304, 325 mesh, 0.0014" Wire, 0.0017" opening) was key to avoiding particulate contamination during parylene deposition.

Table. 1. Parylene C deposition parameters per Marvell Nanolab manual: http://nanolab.berkeley.edu/labmanual/chap6/6.22parylene.pdf.

T <sub>furnace</sub>	T <sub>chamber</sub>	T <sub>vaporizer</sub>	P <sub>chamber</sub>	Mass
[°C]	[°C]	[°C]	[mTorr]	[g]
360	57	80	25	3

The conductor was patterned in a bi-layer lift-off process. A 1.3  $\mu$ m thick layer of G-line resist (OCG 825) was spun at 5000 RPM on top of the Parylene. The wafer was soft baked at 90 °C for 60 seconds and flood exposed (Karl Suss MA6

0.14 J/cm<sup>2</sup>). A layer of I-line photoresist (OiR 10i 1.1 μm thick) was then spun at 4100 RPM and soft baked at 90 °C. The wafer was exposed with a dose of  $0.06 \text{ J/cm}^2$  and developed in OPD 4262 for 60 s. A 20 s etch in oxygen plasma (80 sccm and 200 W RF power) was performed in the Plasma-Therm PK-12 RIE tool to de-scum the surface and improve adhesion for metal deposition. For the prototype devices, a tri-stack of metal (10 nm Cr / 200 nm Au / 50 nm Pt) was electron-beam (e-beam) evaporated. Fabrication of the hybrid devices required two separate deposition and lift-off steps: A stack of two metal layers (10 nm Cr / 100 nm Au) was e-beam evaporated. The metal was lifted-off by soaking in acetone for 10 min. After a second lithographic step, ITO was sputtered from an In2O3:SnO2 (10 wt% SnO<sub>2</sub>) target in Edwards Auto 306 DC and RF Sputter Coater in argon (Ar) at a pressure of 2.2 mTorr (base pressure:  $4 \cdot 10^{-5}$  Torr) and a DC power density of  $1 \text{ W/cm}^2$ , yielding a 110 nm thick layer (sputter time: 33 min, deposition rate: 3.3 nm/min). Lift-off was performed followed by another de-scum etch, as described A thin adhesion layer of  $\gamma$ -MPS above. (γmethacryloxypropyltrimethoxysilane) was deposited through AMST Molecular Vapor Deposition System MVD100 and another 3 µm thick Parylene layer was deposited. The vias and a device outline were patterned through two separated photolithography steps and oxygen plasma etching (200 W, 73 mTorr, 15 x 30 s intervals with 30 s cool-down period in Plasma-Therm PK-12 RIE). Finally, the devices were released from the silicon carrier wafer in a mild solution of detergent in deionized water. Micrographs and SEM images of the fabrication results are shown in Figure 4.

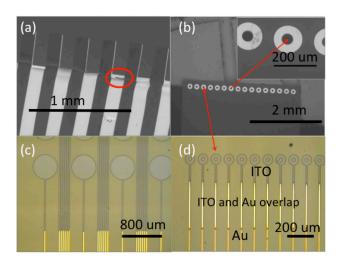


Fig. 4. Micrographs and SEM images of the 16-channel and 49-channel devices. (a) Bond pad damage on ITO-only devices. (b) Intact electrodes of a 16-channel ITO device. (c) Electrodes and interconnects of a 49-channel Au-ITO hybrid device. (d) 16-channel hybrid array. The ring-shaped electrodes are made of ITO. The light yellow lines indicate the overlap of Au and ITO. The lower part of the connections consists of Cr/Au.

# B. Assembly and Packaging

A fan-out PCB with 3-mil-trace/space was

manufactured by Sierra Circuits to connect a 1D array of ACF bonding pads (pad dimensions:  $100 \,\mu\text{m} \times 2500 \,\mu\text{m}$ , 200  $\mu\text{m}$  pitch) to two footprints of surface mount Hirose connectors (DF30FC-34DS-0.4V).

The wafer level devices were bonded to the PCB in an ACF process as shown in Fig. 3 (right). ACF (3M 5552R, 2 mm wide) was pre-bonded to the corresponding PCB footprint using an Ohashi HMB-10 table-top bonder equipped with a 2.5 mm wide bond head (1 s, 90 °C, 5 kg/cm<sup>2</sup>). Parylene devices were aligned under a stereomicroscope using a custom alignment system comprising two vacuum chucks mounted on  $\theta xyz$  -micropositioners, and tacked to the ACF film with a soldering iron. The final bond was performed using the HMB-10 (20 s, 200 °C, 40 kg/cm<sup>2</sup>).

# IV. RESULTS

### A. Optical properties of ITO film

Transparency was measured using an ellipsometer/spectrometer (Sopra GESP) under normal incidence. The transmittance, normalized with respect to the substrate, exceeded 90% over most of the visible spectrum (Fig. 5).

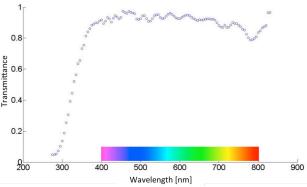


Fig. 5. Transmittance of the 110 nm thin ITO film is shown as a function of wavelength (285 nm to 830 nm).

### B. Electrical Characterization

The sheet resistance of the ITO was determined to be 43.7  $\Omega$ /square in a 4-point-probe (VEECO FPP-5000) measurement. The resistivity was calculated to be  $4.807 \times 10^{-6} \Omega m$ . ITO traces in our design are between 1 mm and 6.5 mm in length. Thus, from device geometry, we expected a series resistance between 2.2 k $\Omega$  and 14.2 k $\Omega$  for each electrode.

We characterized the electrode/electrolyte interface by electrochemical impedance spectroscopy (EIS) (*nanoZ*<sup>TM</sup>, White Matter, LLC, frequency sweep: 5 Hz to 5 kHz). The device formed the active electrode and a silver wire formed the reference electrode. We used artificial cerebrospinal fluid (aCSF, Artificial CSF Perfusion Fluid, Harvard Apparatus, ion concentrations in mM:  $[Na^+] = 150$ ;  $[K^+] = 3.0$ ;  $[Ca^{2+}] = 1.4$ ;  $[Mg^{2+}] = 0.8$ ;  $[PO^{4-}] = 1.0$ ; [CI] = 155) as the electrolyte.

The data were fitted to a Randles Cell model using EIS

Spectrum Analyzer [19] to extract the line resistance  $R_s = 9.36 \pm 5.53 \text{ k}\Omega$ charge transfer resistance  $R_p = 187.29 \pm 56.17 \text{ M}\Omega$  and the parameters of the constant phase element (CPE) parameters  $n = 0.87 \pm 0.002$  and  $P = 1.58 \pm 0.02$  s<sup>n</sup>/( $\Omega$ cm<sup>2</sup>) shown in Fig. 6. The series resistance value was in good agreement with our predictions. Approximating the CPE with a capacitor, we calculated the capacitance per area of the ITO pads to be  $1.39 \pm 0.02 \,\mu\text{F}\,\text{cm}^{-2}$ ) which is an order of magnitude lower than that of platinum pads (60  $\mu$ F cm<sup>-2</sup>) [20]. The parallel resistance was expected to be very high as all testing is performed at voltages far below electrochemical potentials and no Faradaic charge transfer was expected. We calculated a pad-electrolyte interface resistance of  $212 \pm 60 \text{ k}\Omega \text{ cm}^2$  which was similar to values reported for platinum literature  $(220 \text{ k}\Omega \text{ cm}^2)$  [20]. in

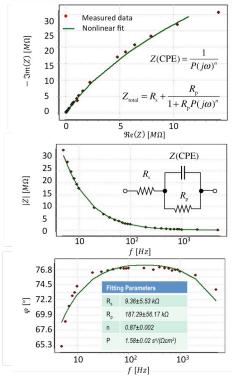


Fig. 6. Characterization of the electrode-electrolyte interface by electrochemical impedance spectroscopy. The data were adequately fit by the Randles Cell circuit model.

### V. CONCLUSION

Conductive and transparent ITO films were successfully DC-sputtered on Parylene and patterned by lift-off. While ITO on Parylene is quite brittle, our approach successfully combined metal interconnects with ITO microelectrodes, resulting in flexible, transparent hybrid  $\mu$ ECoGs with good electrical and excellent optical characteristics.

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